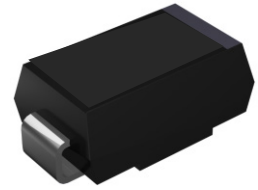


Features

- Glass passivated junction chip
- For surface mounted application
- Low forward voltage drop
- Low profile package
- Built-in strain relief, ideal for automated placement
- Fast switching for high efficiency
- High temperature soldering: 260°C/10 seconds at terminals
- Plastic package has Underwriters Laboratory Flammability Classification 94V-0



DO-214AB (SMC)



Mechanical Data

- Case: Molded plastic
- Terminals: Solder plated
- Polarity: Indicated by cathode end
- Weight: 0.009 ounce, 0.25gram

Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Parameter	Symbol	SN30	Unit
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	1200	V
Maximum RMS Voltage	V _{RMS}	840	V
Maximum DC Blocking Voltage	V _{DC}	1200	V
Maximum Average Forward Rectified Current at T _L =103°C	I _{F(AV)}	3.0	A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load (JEDEC Method) T _L =75°C	I _{FSM}	100.0	A
Typical Thermal Resistance per Case ¹	R _{θJA}	47	°C/W
	R _{θJL}	13	
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Test Conditions	Symbol	SN30	Unit
Maximum Instantaneous Forward Voltage	I _F =3.0A	V _F	1.25	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	T _A =25°C	I _R	10.0	uA
	T _A =125°C		250	
Typical Reverse Recovery Time	I _F =0.5A; I _R =1.0A; I _{tr} =0.25A	t _{rr}	1.0	uS
Typical Junction Capacitance	4.0V, 1MHz	C _J	60	pF

Notes:

1. Thermal resistance from junction to ambient and from junction to lead frame P.C.B. mounted on 0.3×0.3"(8.0×8.0mm) copper pad areas.

Typical Characteristics Curves

Fig. 1 - Forward Current Derating Curve

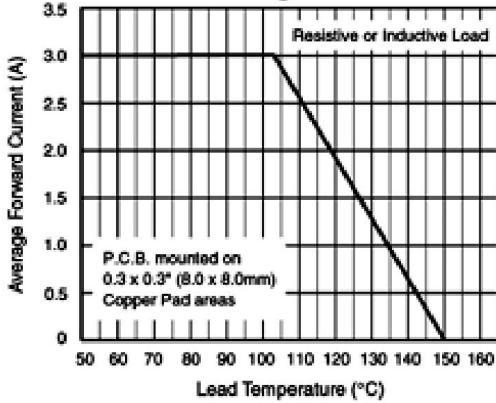


Fig. 2 - Maximum Non-Repetitive Peak Forward Surge Current

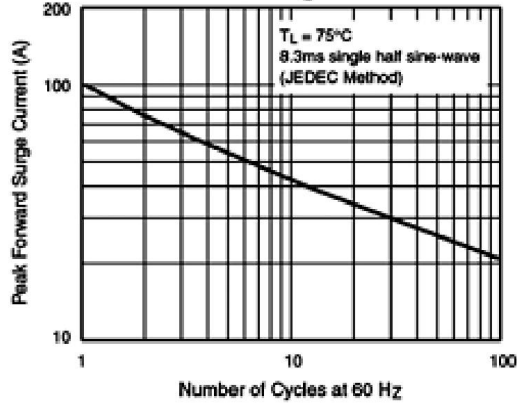


Fig. 3 - Typical Instantaneous Forward Characteristics

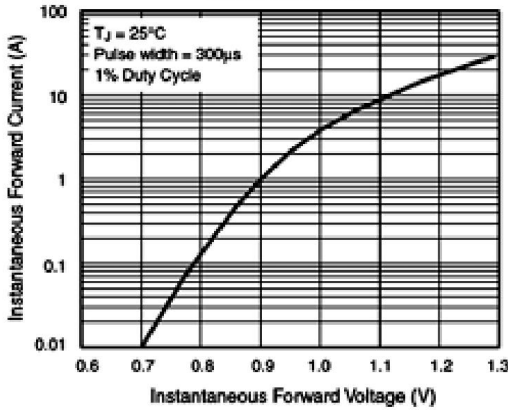


Fig. 4 - Typical Reverse Characteristics

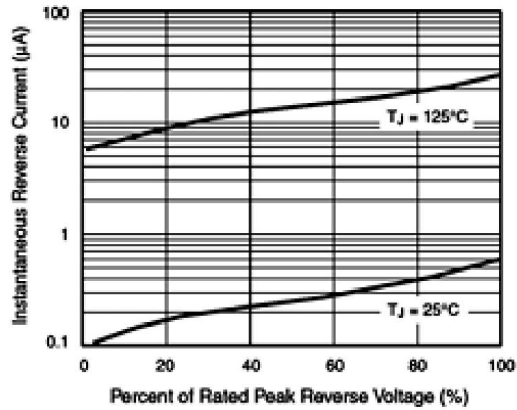


Fig. 5 - Typical Junction Capacitance

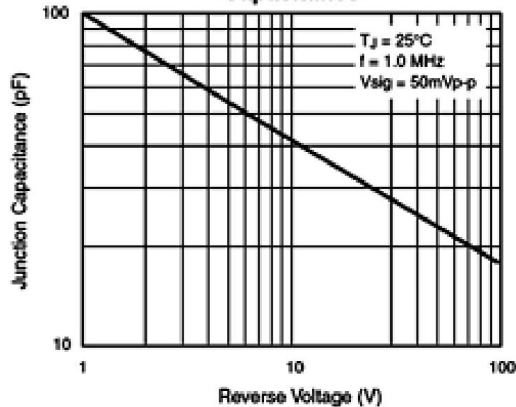
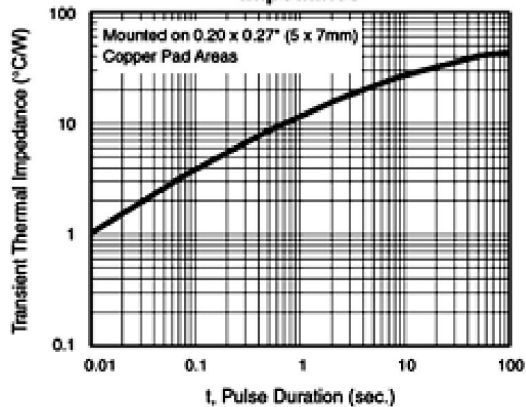
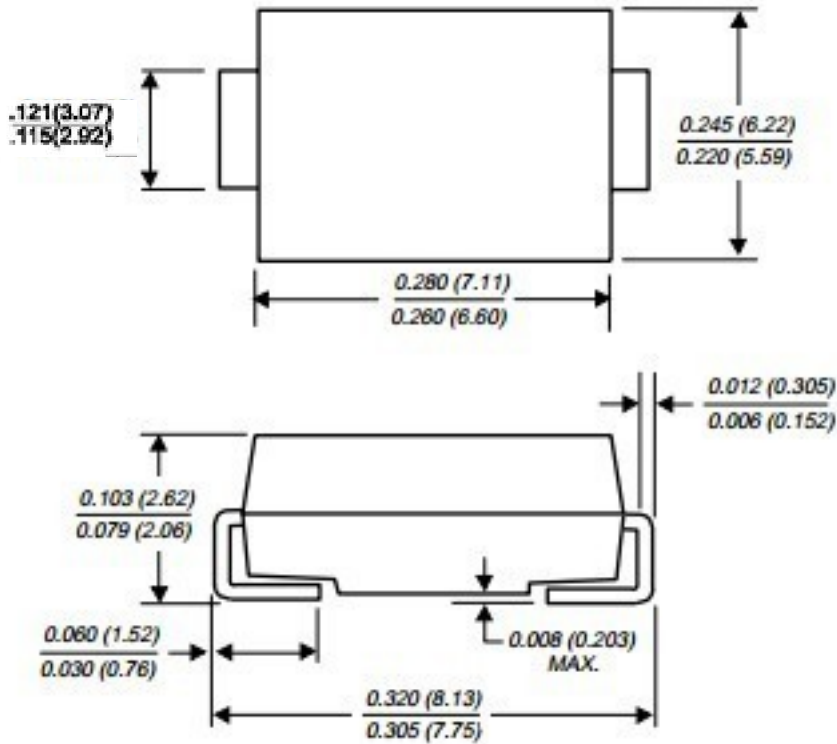


Fig. 6 - Typical Transient Thermal Impedance



Package outline Dimensions DO-214AB (SMC)



Dimensions in inches and (millimeters)